- Dual Versions of Highly Stable SN54121 and SN74121 One Shots
- SN54221 and SN74221 Demonstrate Electrical and Switching Characteristics That Are Virtually Identical to the SN54121 and SN74121 One Shots
- Pinout Is Identical to the SN54123, SN74123, SN54LS123, and SN74LS123
- Overriding Clear Terminates Output Pulse

|  | MAXIMUM <br> OUTPUT |
| :--- | :---: |
| TYPE | PULSE |
| LENGTH(S) |  |

## description/ordering information

The '221 and 'LS221 devices are dual multivibrators with performance characteristics virtually identical to those of the '121 devices. Each multivibrator features a negative-transitiontriggered input and a positive-transition-triggered input, either of which can be used as an inhibit input.

| SN54221, SN54LS221... J PACKAGESN74221... N PACKAGE |  |  |
| :---: | :---: | :---: |
| SN74LS221 ... D, DB, N, OR NS PACKAGE (TOP VIEW) |  |  |
| 1A | $1 \cup_{16}$ | $\mathrm{V}_{\mathrm{CC}}$ |
| 1B | 215 | $1 R_{\text {ext }} / C_{\text {ext }}$ |
| 1 $\overline{C L R}$ | 314 | $1 \mathrm{C}_{\text {ext }}$ |
| 1可 | 413 | 1 Q |
| 2Q | 512 | 2 $\bar{Q}$ |
| $2^{2} \mathrm{Cext}^{\text {l }}$ | 611 | 2 $\overline{C L R}$ |
| $2 \mathrm{R}_{\text {ext }} / \mathrm{C}_{\text {ext }}$ | 710 | 2B |
| GND [ | 8 9 | $2 A$ |

SN54LS221... FK PACKAGE (TOP VIEW)


NC - No internal connection

ORDERING INFORMATION

| $\mathrm{T}_{\text {A }}$ | PACKAGE $\dagger$ |  | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
| :---: | :---: | :---: | :---: | :---: |
| $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ | PDIP - N | Tube | SN74221N | SN74221N |
|  |  |  | SN74LS221N | SN74LS221N |
|  | SOIC - D | Tube | SN74LS221D | LS221 |
|  |  | Tape and reel | SN74LS221DR |  |
|  | SOP - NS | Tape and reel | SN74LS221NSR | 74LS221 |
|  | SSOP - DB | Tape and reel | SN74LS221DBR | LS221 |
| $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$ | CDIP - J | Tube | SNJ54221J | SNJ54221J |
|  |  |  | SNJ54LS221J | SNJ54LS221J |
|  | LCCC - FK | Tube | SNJ54LS221FK | SNJ54LS221FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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## description/ordering information (continued)

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. Schmitt-trigger input circuitry (TTL hysteresis) for B input allows jitter-free triggering from inputs with transition at rates as slow as $1 \mathrm{~V} / \mathrm{s}$, providing the circuit with excellent noise immunity, typically of 1.2 V . A high immunity to $\mathrm{V}_{\mathrm{CC}}$ noise, typically of 1.5 V , also is provided by internal latching circuitry.
Once fired, the outputs are independent of further transitions of the $A$ and $B$ inputs and are a function of the timing components, or the output pulses can be terminated by the overriding clear. Input pulses can be of any duration relative to the output pulse. Output pulse length can be varied from 35 ns to the maximum by choosing appropriate timing components. With $R_{e x t}=2 \mathrm{k} \Omega$ and $\mathrm{C}_{\mathrm{ext}}=0$, an output pulse typically of 30 ns is achieved that can be used as a dc-triggered reset signal. Output rise and fall times are TTL compatible and independent of pulse length. Typical triggering and clearing sequences are shown as a part of the switching characteristics waveforms.

Pulse-width stability is achieved through internal compensation and is virtually independent of $\mathrm{V}_{\mathrm{CC}}$ and temperature. In most applications, pulse stability is limited only by the accuracy of external timing components.
Jitter-free operation is maintained over the full temperature and $V_{C C}$ ranges for more than six decades of timing capacitance ( 10 pF to $10 \mu \mathrm{~F}$ ) and more than one decade of timing resistance ( $2 \mathrm{k} \Omega$ to $30 \mathrm{k} \Omega$ for the SN54221, $2 \mathrm{k} \Omega$ to $40 \mathrm{k} \Omega$ for the SN74221, $2 \mathrm{k} \Omega$ to $70 \mathrm{k} \Omega$ for the SN54LS221, and $2 \mathrm{k} \Omega$ to $100 \mathrm{k} \Omega$ for the SN74LS221). Throughout these ranges, pulse width is defined by the relationship: $t_{w}$ (out) $=\mathrm{C}_{\text {ext }} R_{\text {ext }} \ln 2 \approx 0.7 \mathrm{C}_{\text {ext }} R_{\text {ext }}$. In circuits where pulse cutoff is not critical, timing capacitance up to $1000 \mu \mathrm{~F}$ and timing resistance as low as $1.4 \mathrm{k} \Omega$ can be used. Also, the range of jitter-free output pulse widths is extended if $\mathrm{V}_{\mathrm{CC}}$ is held to 5 V and free-air temperature is $25^{\circ} \mathrm{C}$. Duty cycles as high as $90 \%$ are achieved when using maximum recommended $\mathrm{R}_{\mathrm{T}}$. Higher duty cycles are available if a certain amount of pulse-width jitter is allowed.

The variance in output pulse width from device to device typically is less than $\pm 0.5 \%$ for given external timing components. An example of this distribution for the ' 221 is shown in Figure 3. Variations in output pulse width versus supply voltage and temperature for the '221 are shown in Figures 4 and 5, respectively.
Pin assignments for these devices are identical to those of the SN54123/SN74123 or SN54LS123/SN74LS123 so that the '221 or 'LS221 devices can be substituted for those products in systems not using the retrigger by merely changing the value of $R_{\text {ext }}$ and/or $C_{e x t}$; however, the polarity of the capacitor must be changed.
FUNCTION TABLE

| INPUTS |  |  |  | OUTPUTS |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\overline{\text { CLR }}$ | A | B | Q | $\overline{\text { Q }}$ |  |
| L | X | X | L | H |  |
| X | H | X | L | H |  |
| X | X | L | L | H |  |
| H | L | $\uparrow$ | $\Omega^{\dagger}$ | $\mathrm{V}^{\dagger}$ |  |
| H | $\downarrow$ | H | $\Omega^{\dagger}$ | $\mathrm{V}^{\dagger}$ |  |
| $\uparrow \ddagger$ | L | H | $\Omega^{\dagger}$ | $\mathrm{U}^{\dagger}$ |  |

$\dagger$ Pulsed-output patterns are tested during AC switching at $25^{\circ} \mathrm{C}$ with $R_{\text {ext }}=2 \mathrm{k} \Omega$, and $C_{\text {ext }}=80 \mathrm{pF}$.
$\ddagger$ This condition is true only if the output of the latch formed by the two NAND gates has been conditioned to the logic 1 state prior to $\overline{\mathrm{CLR}}$ going high. This latch is conditioned by taking either A high or $B$ low while $\overline{C L R}$ is inactive (high).
timing component connections


NOTE: Due to the internal circuit, the $\mathrm{Rext} / \mathrm{C}_{\text {ext }}$ terminal never is more positive than the $\mathrm{C}_{\text {ext }}$ terminal.

## schematics of inputs and outputs



SN54/74LS221


## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

$$
\begin{aligned}
& \text { Input voltage range, } \mathrm{V}_{\mathrm{I}} \text { (see Note 1): ' }{ }^{\prime} \text { S221 ............................................................. } 7 \text {. } \mathrm{V} \\
& \text { '221 } \\
& 5.5 \mathrm{~V} \\
& \text { Package thermal impedance, } \theta_{\mathrm{JA}} \text { (see Note 2): D package ........................................ } 73^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { DB package ....................................... } 82^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { N package . ............................................ } 67^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { NS package ....................................... } 64^{\circ} \mathrm{C} / \mathrm{W}
\end{aligned}
$$

$\dagger$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.
recommended operating conditions (see Note 3)

|  |  |  | SN54221 |  |  | SN74221 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | NOM | MAX | MIN | NOM | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| ${ }^{\mathrm{IOH}}$ | High-level output current |  |  |  | -800 |  |  | -800 | $\mu \mathrm{A}$ |
| lOL | Low-level output current |  |  |  | 16 |  |  | 16 | mA |
| $\Delta \mathrm{V} / \Delta \mathrm{t}$ | Rise or fall of input pulse rate | B input | $1^{*}$ |  |  | 1 |  |  | V/s |
|  |  | A input | $1^{*}$ |  |  | 1 |  |  | V/us |
| $\mathrm{T}_{\mathrm{A}}$ | Operating free-air temperature |  | -55 |  | 125 | 0 |  | 70 | ${ }^{\circ} \mathrm{C}$ |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

NOTE 3: All unused inputs of the device must be held at $\mathrm{V}_{\mathrm{CC}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER |  | TEST CONDITIONS $\dagger$ |  | SN54221 |  |  | SN74221 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYPキ | MAX | MIN | TYPキ | MAX |  |
| $\mathrm{V}^{\text {+ }+}$ | Positive-going threshold voltage, B input |  |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$ |  | 1.55 2* |  |  | 1.55 |  | 2 | V |
| $\mathrm{V}_{\mathrm{T} \text { - }}$ | Negative-going threshold voltage, B input | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$ |  | 0.8* | 1.35 |  | 0.8 | 1.35 |  | V |
| $\mathrm{V}_{\text {IK }}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$, | $\boldsymbol{I}=-12 \mathrm{~mA}$ | -1.5 |  |  | -1.5 |  |  | V |
| $\mathrm{V}_{\mathrm{OH}}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$, | $\mathrm{l} \mathrm{OH}=-800 \mu \mathrm{~A}$ | 2.4 | 3.4 |  | 2.4 | 3.4 |  | V |
| $\mathrm{V}_{\mathrm{OL}}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$, | $\mathrm{IOL}=16 \mathrm{~mA}$ |  | 0.2 | 0.4 |  | 0.2 | 0.4 | V |
| I |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MAX}$, | $\mathrm{V}_{\mathrm{I}}=5.5 \mathrm{~V}$ |  |  | 1 |  |  | 1 | mA |
| ${ }^{\text {I H }}$ | A input | $V_{C C}=M A X$, | $\mathrm{V}_{\mathrm{I}}=2.4 \mathrm{~V}$ |  |  | 40 |  |  | 40 | $\mu \mathrm{A}$ |
|  | $\overline{\mathrm{CLR}}, \mathrm{B}$ input |  |  |  |  | 80 |  |  | 80 |  |
| IIL | A input | $V_{C C}=$ MAX, | $\mathrm{V}_{\mathrm{I}}=0.4 \mathrm{~V}$ |  |  | -1.6 |  |  | -1.6 | mA |
|  | $\overline{\text { CLR, }} \mathrm{B}$ input |  |  |  |  | -3.2 |  |  | -3.2 |  |
| los§ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MAX}$ |  | -20 |  | -55 | -18 |  | -55 | mA |
|  | Quiescent | VCo = MAX |  |  | 26 | 50* |  | 26 | 50 | mA |
| ${ }^{\text {c }}$ | Triggered | $V_{C C}=$ MAX |  |  | 46 | 80* |  | 46 | 80 | mA |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
$\dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
$\ddagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
timing requirements over recommended ranges of supply voltage and operating free-air temperature

|  |  |  | SN5 | 221 | SN7 |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX |  |
|  | Pu | A or B input | 50 |  | 50 |  |  |
| $t_{\text {w }}$ | se duration | $\overline{\mathrm{CLR}}$ | 20 |  | 20 |  |  |
| $\mathrm{t}_{\text {su }}$ | Setup time, inactive-state\I | $\overline{\mathrm{CLR}}$ | 15 |  | 15 |  | ns |
| $\mathrm{R}_{\text {ext }}$ | External timing resistance |  | 1.4* | 30* | 1.4 | 40 | $\mathrm{k} \Omega$ |
| $\mathrm{C}_{\text {ext }}$ | External timing capacitance |  | 0* | 1000* | 0 | 1000 | $\mu \mathrm{F}$ |
|  |  | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ |  | 67\% |  | 67\% |  |
|  | Output duty cycle | $\mathrm{R}_{\text {ext }}=$ MAX R ${ }_{\text {ext }}$ |  | 90\% |  | 90\% |  |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

II Inactive-state setup time also is referred to as recovery time.
switching characteristics $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=400 \Omega, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ (see Figures 1 and 2)

| PARAMETER | FROM (INPUT) | $\begin{gathered} \text { TO } \\ \text { (OUTPUT) } \end{gathered}$ | TEST CONDITIONS |  | SN54221 |  |  | SN74221 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  | MIN | TYP | MAX | MIN | TYP | MAX |  |
| tPLH | A | Q | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ |  | 45 | 70 |  | 45 | 70 | ns |
|  | B |  |  |  |  | 35 | 55 |  | 35 | 55 |  |
| tPHL | A | $\overline{\mathrm{Q}}$ |  |  |  | 50 | 80 |  | 50 | 80 |  |
|  | B |  |  |  |  | 40 | 65 |  | 40 | 65 |  |
| tPHL | $\overline{C L R}$ | Q | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ |  |  | 27 |  |  | 27 | ns |
| tPLH |  | $\bar{Q}$ |  |  |  |  | 40 |  |  | 40 |  |
| $t_{\text {w }}$ | A or B | Q or $\bar{Q}$ | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ | 70 | 110 | 150 | 70 | 110 | 150 | ns |
|  |  |  | $\mathrm{C}_{\text {ext }}=0$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ | 17 | 30 | 50 | 17 | 30 | 50 |  |
|  |  |  | $\mathrm{C}_{\text {ext }}=100 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=10 \mathrm{k} \Omega$ | 650 | 700 | 750 | 650 | 700 | 750 |  |
|  |  |  | $\mathrm{C}_{\text {ext }}=1 \mu \mathrm{~F}$, | $\mathrm{R}_{\text {ext }}=10 \mathrm{k} \Omega$ | 6.5* | 7 | 7.5* | 6.5 | 7 | 7.5 | ms |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
recommended operating conditions (see Note 4)

|  |  |  | SN54LS221 |  |  | SN74LS221 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | NOM | MAX | MIN | NOM | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| ${ }^{\text {IOH }}$ | High-level output current |  |  |  | -400 |  |  | -400 | $\mu \mathrm{A}$ |
| IOL | Low-level output current |  |  |  | 4 |  |  | 8 | mA |
| $\Delta \mathrm{V} / \Delta \mathrm{t}$ | Rise or fall of input pulse rate | B input | $1^{*}$ |  |  | 1 |  |  | V/s |
|  |  | A input | $1^{*}$ |  |  | 1 |  |  | V/us |
| $\mathrm{T}_{\mathrm{A}}$ | Operating free-air temperature |  | -55 |  | 125 | 0 |  | 70 | ${ }^{\circ} \mathrm{C}$ |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

NOTE 4: All unused inputs of the device must be held at $\mathrm{V}_{\mathrm{CC}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER |  | TEST CONDITIONS $\dagger$ |  | SN54LS221 |  |  | SN74LS221 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYPキ | MAX | MIN | TYP\# | MAX |  |
| $\mathrm{V}_{\text {+ }}$ | Positive-going threshold voltage, B input |  |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$ |  |  | 1 | 2* |  | 1 | 2 | V |
| $\mathrm{V}_{\text {T- }}$ | Negative-going threshold voltage, $B$ input | $V_{C C}=\mathrm{MIN}$ |  | 0.7* | 0.9 |  | 0.8 | 0.9 |  | V |
| $\mathrm{V}_{\text {IK }}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$, | $\boldsymbol{I}=-18 \mathrm{~mA}$ | -1.5 |  |  | -1.5 |  |  | V |
| $\mathrm{V}_{\mathrm{OH}}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$, | $\mathrm{IOH}=-400 \mu \mathrm{~A}$ | 2.5 | 3.4 |  | 2.7 | 3.4 |  | V |
| $\mathrm{V}_{\mathrm{OL}}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MIN}$ | $\mathrm{IOL}=4 \mathrm{~mA}$ |  | 0.25 | 0.4 |  | 0.25 | 0.4 | V |
|  |  | $\mathrm{OL}=8 \mathrm{~mA}$ |  |  |  |  | 0.35 | 0.5 |  |
| 1 |  |  | $V_{C C}=$ MAX, | $\mathrm{V}_{\mathrm{I}}=7 \mathrm{~V}$ |  |  | 0.1 |  |  | 0.1 | mA |
| IIH |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MAX}$, | $\mathrm{V}_{\mathrm{l}}=2.7 \mathrm{~V}$ |  |  | 20 |  |  | 20 | $\mu \mathrm{A}$ |
|  | A input |  |  |  |  | -0.4 |  |  | -0.4 |  |
| IIL | $\overline{\mathrm{CLR}}$, B input | $V_{C C}=$ MAX, | $\mathrm{V}=0.4 \mathrm{~V}$ |  |  | -0.8 |  |  | -0.8 | mA |
| $\mathrm{l}^{\text {OS }}$ |  | $\mathrm{V}_{\mathrm{CC}}=\mathrm{MAX}$ |  | -20 |  | -100 | -20 |  | -100 | mA |
|  | Quiescent | VCC = MAX |  |  | 4.7 | 11 |  | 4.7 | 11 | mA |
| ICC | Triggered | VCC = MAX |  |  | 19 | 27* |  | 19 | 27 |  |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
$\dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
$\ddagger$ All typical values are at $\mathrm{V}_{\mathrm{C}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
timing requirements over recommended ranges of supply voltage and operating free-air temperature

|  |  |  | SN54L | S221 | SN74 | S221 |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX | UNT |
|  |  | A or B | 50 |  | 50 |  |  |
| ${ }_{\text {t }}$ w | ulse duration | $\overline{\overline{C L R}}$ | 40 |  | 40 |  | ns |
| $\mathrm{t}_{\text {su }}$ | Setup time, inactive state ${ }^{\text {I }}$ | $\overline{\mathrm{CLR}}$ | 15 |  | 15 |  | ns |
| $\mathrm{R}_{\text {ext }}$ | External timing resistance |  | 1.4* | 70* | 1.4 | 100 | $\mathrm{k} \Omega$ |
| Cext | External timing capacitance |  | 0* | 1000* | 0 | 1000 | $\mu \mathrm{F}$ |
|  | put duty cycle | $\mathrm{R} T=2 \mathrm{k} \Omega$ |  | 50\% |  | 50\% |  |
|  | dit duty cycle | $\mathrm{R}_{\mathrm{T}}=$ MAX R ${ }_{\text {ext }}$ |  | 90\% |  | 90\% |  |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

II Inactive-state setup time also is referred to as recovery time.
switching characteristics $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=2 \mathrm{k} \Omega, \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ (see Figures 1 and 2)

| PARAMETER | $\begin{aligned} & \text { FROM } \\ & \text { (INPUT) } \end{aligned}$ | $\begin{gathered} \text { TO } \\ \text { (OUTPUT) } \end{gathered}$ | TEST CONDITIONS |  |  | 4LS2 |  |  | 4LS2 |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  | MIN | TYP | MAX | MIN | TYP | MAX |  |
| tPLH | A | Q | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\mathrm{ext}}=2 \mathrm{k} \Omega$ |  | 45 | 70 | 45 70 <br> 35 55 <br> 50 80 <br> 40 65 |  |  | ns |
|  | B |  |  |  |  | 35 | 55 |  |  |  |  |
| tPHL | A | $\bar{Q}$ |  |  |  | 50 | 80 |  |  |  |  |
|  | B |  |  |  |  | 40 | 65 |  |  |  |  |
| tPHL | $\overline{C L R}$ | Q | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\mathrm{ext}}=2 \mathrm{k} \Omega$ |  | 35 | 55 |  | 35 | 55 | ns |
| tPLH |  | $\bar{Q}$ |  |  |  | 44 | 65 |  | 44 | 65 |  |
| $t_{\text {w }}$ | A or B | Q or $\overline{\mathrm{Q}}$ | $\mathrm{C}_{\text {ext }}=80 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ | 70 | 120 | 150 | 70 | 120 | 150 | ns |
|  |  |  | $\mathrm{C}_{\text {ext }}=0$, | $\mathrm{R}_{\text {ext }}=2 \mathrm{k} \Omega$ | 20 | 47 | 70 | 20 | 47 | 70 |  |
|  |  |  | $\mathrm{C}_{\text {ext }}=100 \mathrm{pF}$, | $\mathrm{R}_{\text {ext }}=10 \mathrm{k} \Omega$ | 670 | 740 | 810 | 670 | 740 | 810 |  |
|  |  |  | $\mathrm{C}_{\text {ext }}=1 \mu \mathrm{~F}$, | $\mathrm{R}_{\text {ext }}=10 \mathrm{k} \Omega$ | $6^{*}$ | 6.9 | 7.5* | 6 | 6.9 | 7.5 | ms |

[^0]

CONDITION 2: TRIGGER FROM B, THEN $\overline{C L R}$

$\dagger \mathrm{A}$ is low.
Figure 1. Switching Characteristics


CONDITION 4: TRIGGERING FROM POSITIVE TRANSITION OF $\overline{C L R}$


CONDITION 5: TRIGGER FROM A, THEN $\overline{C L R}$

$\dagger \mathrm{A}$ is low.
$\ddagger B$ and CLR are high.
NOTES: A. Input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 1 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}} \approx 50 \Omega$; for $\mathrm{SN} 54 / 74221, \mathrm{t}_{\mathrm{r}} \leq 7 \mathrm{~ns}$, $\mathrm{t}_{\mathrm{f}} \leq 7 \mathrm{~ns}$, for $\mathrm{SN} 54 / 74 \mathrm{LS} 221, \mathrm{t}_{\mathrm{r}} \leq 15 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 6 \mathrm{~ns}$.
B. All measurements are made between the 1.5-V points of the indicated transitions for the SN54/74221 or between the 1.3-V points for the SN54/74LS221.

Figure 1. Switching Characteristics (Continued)


NOTES: A. $C_{L}$ includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
D. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 1 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}} \approx 50 \Omega$ and, for $\mathrm{SN} 54 / 74221$, $\mathrm{t}_{\mathrm{r}} \leq 7 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 7 \mathrm{~ns}$, for SN54/74LS221, $\mathrm{t}_{\mathrm{r}} \leq 15 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 6 \mathrm{~ns}$.
E. All measurements are made between the $1.5-\mathrm{V}$ points of the indicated transitions for the SN54/74221 or between the $1.3-\mathrm{V}$ points for the SN54/74LS221.

Figure 2. Load Circuits and Voltage Waveforms

## TYPICAL CHARACTERISTICS (SN54/74221 ONLY) $\dagger$



Figure 3


Figure 5

VARIATION IN OUTPUT PULSE
vs
SUPPLY VOLTAGE


Figure 4


Figure 6
$\dagger$ Data for temperatures below $0^{\circ} \mathrm{C}$ and above $70^{\circ} \mathrm{C}$, and for supply voltages below 4.75 V and above 5.25 V are applicable for the SN54221 only. NOTE A: These values of resistance exceed the maximum recommended for use over the full military temperature range of the SN54221.

## PACKAGING INFORMATION

| Orderable Device | Status ${ }^{(1)}$ | Package Type | Package Drawing |  | Package Qty | Eco Plan ${ }^{(2)}$ | Lead/Ball Finish | MSL Peak Temp ${ }^{(3)}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 5962-8771101EA | ACTIVE | CDIP | $J$ | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| 76042012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N/ A for Pkg Type |
| 7604201 EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| 7604201FA | ACTIVE | CFP | W | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/31402B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N/ A for Pkg Type |
| JM38510/31402BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/31402BFA | ACTIVE | CFP | W | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| SN54221J | ACTIVE | CDIP | $J$ | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| SN54LS221J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| SN74221N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/A for Pkg Type |
| SN74221NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type |
| SN74LS221D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DBR | ACTIVE | SSOP | DB | 16 | 2000 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br} \text { ) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DBRE4 | ACTIVE | SSOP | DB | 16 | 2000 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br} \text { ) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DBRG4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br})$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DE4 | ACTIVE | SOIC | D | 16 | 40 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br} \text { ) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DG4 | ACTIVE | SOIC | D | 16 | 40 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br}) \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DR | ACTIVE | SOIC | D | 16 | 2500 | $\begin{gathered} \hline \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br}) \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DRE4 | ACTIVE | SOIC | D | 16 | 2500 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br}) \\ \hline \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221DRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type |
| SN74LS221N3 | OBSOLETE | PDIP | N | 16 |  | TBD | Call TI | Call TI |
| SN74LS221NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type |
| SN74LS221NSR | ACTIVE | SO | NS | 16 | 2000 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no Sb/Br) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221NSRE4 | ACTIVE | SO | NS | 16 | 2000 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br} \text { ) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS221NSRG4 | ACTIVE | SO | NS | 16 | 2000 | $\begin{gathered} \text { Green (RoHS \& } \\ \text { no } \mathrm{Sb} / \mathrm{Br} \text { ) } \end{gathered}$ | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ54221J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N/ A for Pkg Type |
| SNJ54LS221FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N/ A for Pkg Type |
| SNJ54LS221J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N/ A for Pkg Type |
| SNJ54LS221W | ACTIVE | CFP | W | 16 | 1 | TBD | A42 | N/ A for Pkg Type |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but Tl does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS \& no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb -Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, Tl Pb -Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS \& no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants ( Br or Sb do not exceed $0.1 \%$ by weight in homogeneous material)
${ }^{(3)}$ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package <br> Type | Package <br> Drawing | Pins | SPQ | Reel <br> Diameter <br> $(\mathbf{m m})$ | Reel <br> Width <br> W1 $(\mathbf{m m})$ | A0 $(\mathbf{m m})$ | B0 $(\mathbf{m m})$ | K0 $(\mathbf{m m})$ | P1 <br> $(\mathbf{m m})$ | W <br> $(\mathbf{m m})$ | Pin1 <br> Quadrant |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74LS221DBR | SSOP | DB | 16 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LS221DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LS221NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74LS221DBR | SSOP | DB | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74LS221DR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74LS221NSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |



| DIM PINS ** | $\mathbf{1 4}$ | $\mathbf{1 6}$ | $\mathbf{2 0}$ | $\mathbf{2 4}$ | $\mathbf{2 8}$ | $\mathbf{3 0}$ | $\mathbf{3 8}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| A MAX | 6,50 | 6,50 | 7,50 | 8,50 | 10,50 | 10,50 | 12,90 |
| A MIN | 5,90 | 5,90 | 6,90 | 7,90 | 9,90 | 9,90 | 12,30 |

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150


| DIM PINS ** | 14 | 16 | 18 | 20 |
| :---: | :---: | :---: | :---: | :---: |
| A | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC |
| B MAX | 0.785 <br> $(19,94)$ | .840 <br> $(21,34)$ | 0.960 <br> $(24,38)$ | 1.060 <br> $(26,92)$ |
| B MIN | - | - | - | - |
| C MAX | 0.300 <br> $(7,62)$ | 0.300 <br> $(7,62)$ | 0.310 <br> $(7,87)$ | 0.300 <br> $(7,62)$ |
| C MIN | 0.245 <br> $(6,22)$ | 0.245 <br> $(6,22)$ | 0.220 <br> $(5,59)$ | 0.245 <br> $(6,22)$ |



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

NS (R-PDSO-G**)
14-PINS SHOWN


| DIM PINS ** | 14 | 16 | 20 | 24 |
| :---: | :---: | :---: | :---: | :---: |
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F16)


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

D (R-PDSO-G16) PLASTIC SMALL-OUTLINE PACKAGE


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed $.006(0,15)$ per end.
D Body width does not include interlead flash. Interlead flash shall not exceed $.017(0,43)$ per side.
E. Reference JEDEC MS-012 variation AC.

## D(R-PDSO-G16)



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)
PLASTIC DUAL-IN-LINE PACKAGE
16 PINS SHOWN


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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